


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H563IIK6	20MR*484XXX	A	9991	13-07-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	111.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	96.5SN/3.5AG_0.20MM	

Package Designator	Size	Nbr of instances	Shape	
BGA	10x10	201	bulk solder	
Comment	Package : A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	20MR*484XXXX				5999999.0	999998.7
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.027	mg	supplier	die	Silicon (Si)	7440-21-3		1.656	mg	816971	14919
				supplier	metallization	Aluminium (Al)	7429-90-5		0.044	mg	21707	396
				supplier	metallization	Copper (Cu)	7440-50-8		0.138	mg	68081	1243
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	493	9
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	10853	198
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1973	36
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	493	9
Substrate (A299410)	M-011 Other inorganic materials	40.183	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	79428	1450
				supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Undisclosed		3.817	mg	95000	34391
				supplier	BT-substrate	Glass cloth	65997-17-3		10.247	mg	255000	92312
				supplier	BT-substrate	Copper foil	7440-50-8		15.470	mg	385000	139373
				supplier	Solder mask	3-methoxy-3-methylbutylacetate	03429-90-9		5.626	mg	140000	50681
				supplier	Solder mask	Morpholinederivative	Trade secret		1.025	mg	25500	9231
				supplier	Solder mask	Barium Sulfate	7727-43-7		0.782	mg	19450	7041
DAF (ATB-125)	M-011 Other inorganic materials	2.965	mg	supplier	Solder mask	Talc containing no as bestifrom fibers	14807-96-6		0.826	mg	20550	7439
				supplier	Solder mask	Dipropylene glycol monomethyl ether	34590-94-8		2.391	mg	59500	21540
				supplier	film	Butadiene, acrylonitrile polymer, carboxy-term	68610-41-3		2.069	mg	697750	18638
				supplier	film	Formaldehyde, polymer with (chloromethyl)ox	37382-79-9		0.862	mg	290750	7786
				supplier	film	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.017	mg	5750	154
Bonding wire (CuPd)	Precious metals	1.163	mg	supplier	film	Reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.017	mg	5750	154
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.003	mg	3000	31
				supplier	Bonding wire	Copper (Cu)	7440-50-8		1.136	mg	977000	10236
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.023	mg	20000	210
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	59.774	mg	supplier	Molding Compound	Epoxy resin	Trade secret		3.347	mg	56000	30156
				supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		53.797	mg	900000	484654
				supplier	Molding Compound	Phenol resin	Trade secret		2.391	mg	40000	21540
				supplier	Molding Compound	Carbon Black	1333-86-4		0.239	mg	4000	2154
Solderballs (96.5Sn/3.5Ag)	Solder	4.888	mg	supplier	Solder	Tin (Sn)	7440-31-5		4.717	mg	965000	42495
				supplier	Solder	Silver (Ag)	7440-22-4		0.171	mg	35000	1541